

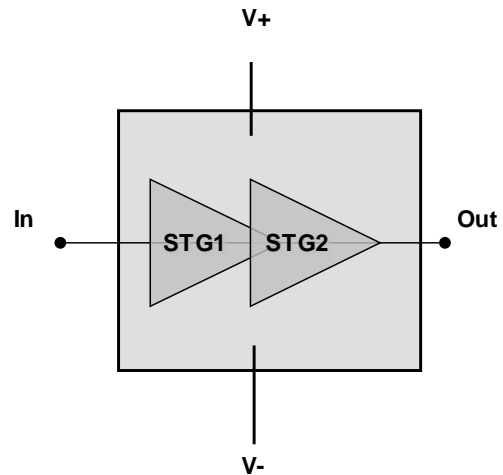
17W X-Band High Power Amplifier

GaN Monolithic Microwave IC

Description

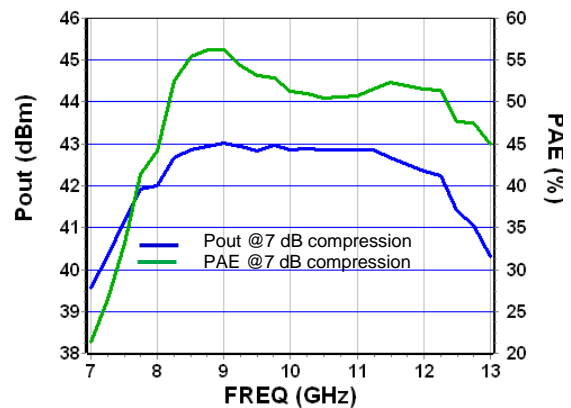
The CHA8312-99F is a two-stage GaN High Power Amplifier in the frequency band 8-12GHz. This HPA typically provides 17W of output power associated to 50% of Power Added Efficiency. The small signal gain exhibits more than 26dB. The overall power supply is of 20V / 320mA (quiescent current). This circuit is a very versatile amplifier for high performance systems.

The circuit is dedicated to defence applications and well suited for a wide range of microwave applications and systems such as radar, test equipment and communication. The part is developed on a robust 0.15 μ m gate length GaN HEMT process over SiC and is available as a bare die.



Main Features

- 8-12GHz frequency range
- Linear Gain is 26dB
- 42.5dBm Pout for +23dBm input power
- Associated PAE is more than 50 % for +23dBm input power
- Associated Id is 1.8A for +23dBm input power
- DC bias: Vd=20V @ Idq= 320mA
- Chip size 3.99x3.12x0.07mm



Main Electrical Characteristics

Tb.= +25°C

Symbol	Parameter	Min	Typ	Max	Unit
Freq	Frequency range	8		12	GHz
Gain	Linear Gain		26		dB
PAE	Power Added Efficiency (Pin = 23dBm)		50		%
Pout	Output Power (Pin = 23dBm)		42.5		dBm

Specifications

Tb.= +25°C, Vd = +20V, Idq = 320mA

Symbol	Parameter	Min	Typ	Max	Unit
Freq	Frequency range	8		12	GHz
Gain	Linear Gain		26		dB
Pout	Output Power (Pin = 23dBm)		42.5		dBm
PAE	Associated Power Added Efficiency (Pin = 23dBm)		50		%
Id	Associated current (Pin = 23 dBm)		1.8		A
S11	Input Return Loss		> 17		dB
S22	Output Return Loss		> 11		dB
Idq	Quiescent Current		320		mA
Vd	Drain Voltage		20		V
Vg	Gate Voltage		-2.94		V

These values are representative of measurements done in test fixture with a bonding wire of typically 0.25 to 0.3nH.

Recommended Operating Ratings

Tb.= +25°C

Symbol	Parameter	Values	Unit
Vd	Drain bias voltage	20	V
Id	Drain bias current	320	mA
Pin	Maximum peak input power overdrive	25	dBm
Tj	Maximum Junction temperature ⁽¹⁾	200	°C

⁽¹⁾ value provided for Tb=85°C

Absolute Maximum Ratings ⁽²⁾

Tb.= +25°C

Symbol	Parameter	Values	Unit
Vd	Drain bias voltage	27	V
Id_north	Drain bias current (north)	1.3	A
Id_south	Drain bias current (south)	1.3	A
Pin	Maximum peak input power overdrive	28	dBm

⁽²⁾ Operation of this device above any one of these parameters may cause permanent damage.

Temperature Range

Tb	Operating temperature range (chip backside temperature reference)	-40 to +85	°C
Tstg	Storage temperature range	-55 to +150	°C

Typical Bias Conditions

Tb.= +25°C

Symbol	Pad N°	Parameter	Values	Unit
VG1	3, 15	Gate voltage tuned for Idq ~ 0.32A	-2.94	V
VG2	5, 13			
VD	4, 7, 11, 14	Drain Voltage	20	V

“Power ON” sequence

1. Bias HPA gate voltage at Vg close to Vpinch-off (example: Vg ≈ -5V).
2. Apply Vd bias voltage (Example: Vd = 20V).
3. Increase Vgs up to quiescent bias drain current Ids0 (320mA applied on the gate).
4. Apply RF signal

“Power OFF” sequence

1. Turn off RF signal
2. Bias HPA gate voltage at Vg close to Vpinch-off (example: Vg ≈ -5V)
3. Set Vd to 0V.
4. Turn off Vd supply.
5. Turn off Vg supply.

Device thermal information

The device thermal performances below are based on UMS rules to evaluate the junction temperature.

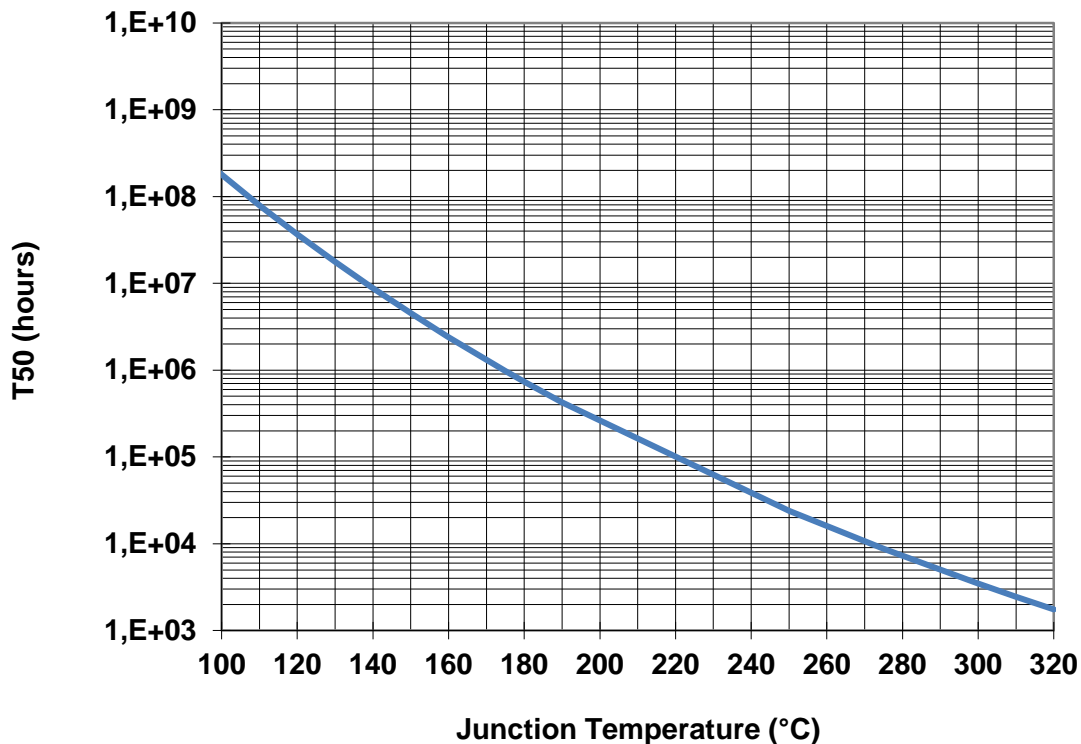
This same procedure is the basis for junction temperature evaluation of the samples used to derive the Median lifetime and activation energy for the particular technology on which the CHA8312-99F is manufactured (GaN HEMT 0.15 μ m).

The temperature $T_{b_{chip}}$ is defined as the chip backside temperature. The thermal resistance (R_{th_eq}) is given for the full circuit, and assumes CW mode is given in the table.

Thermal Resistance ⁽¹⁾	R_{th_eq}	$T_{b_{chip}} = 85^{\circ}\text{C}$, $V_d = 20\text{V}$, $I_{d_drive} = 1.8\text{A}$ $P_{in} = 24\text{dBm}$, $P_{out} = 42.4\text{dBm}$ $P_{diss} = 18.7\text{W CW}$	2.37	$^{\circ}\text{C/W}$
Junction Temperature	T_j		136	$^{\circ}\text{C}$
Median Life	T_{50}		1E07	Hrs

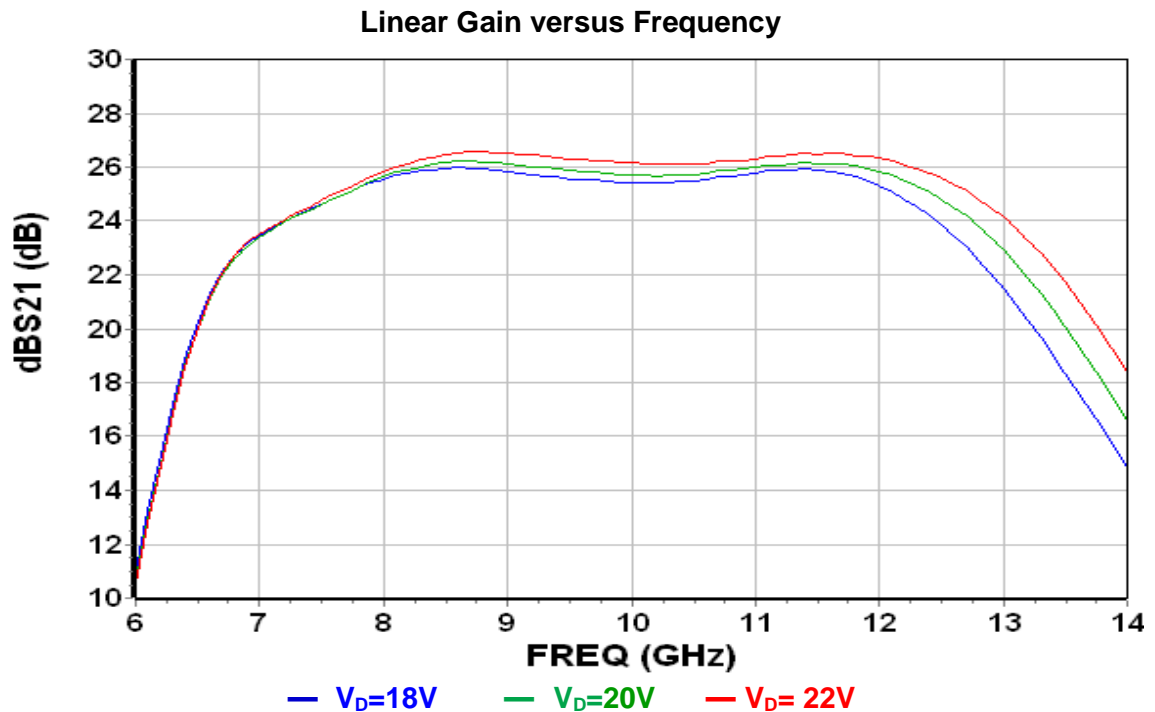
⁽¹⁾ Thermal resistance measured at the back of the chip

Median Life Time versus Junction Temperature

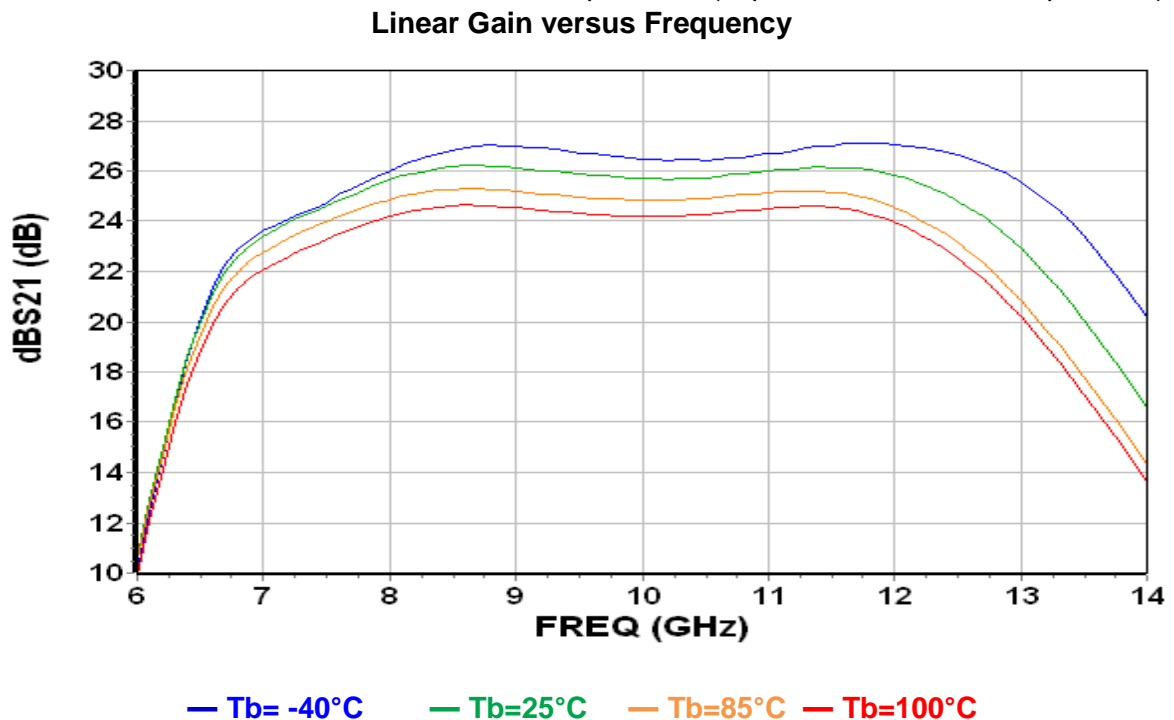


Typical Test Fixture Measurements: Small Signal Performances

Pulsed measurements (25 μ s / 10% Duty Cycle): $T_b = 25^\circ\text{C}$, $I_{dq} = 320\text{mA}$



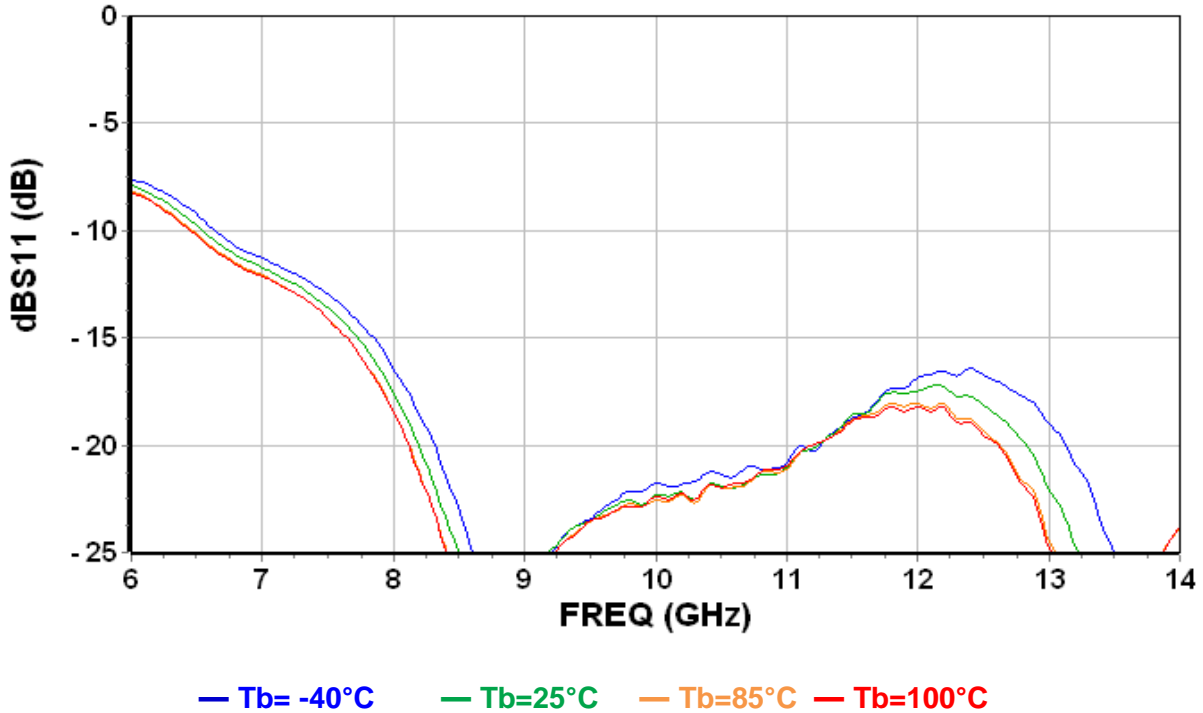
$T_b = -40^\circ\text{C}/+25^\circ\text{C}/+85^\circ\text{C}/100^\circ\text{C}$, $V_d = 20\text{V}$, $I_{dq}=320\text{mA}$ (kept constant versus temperature)



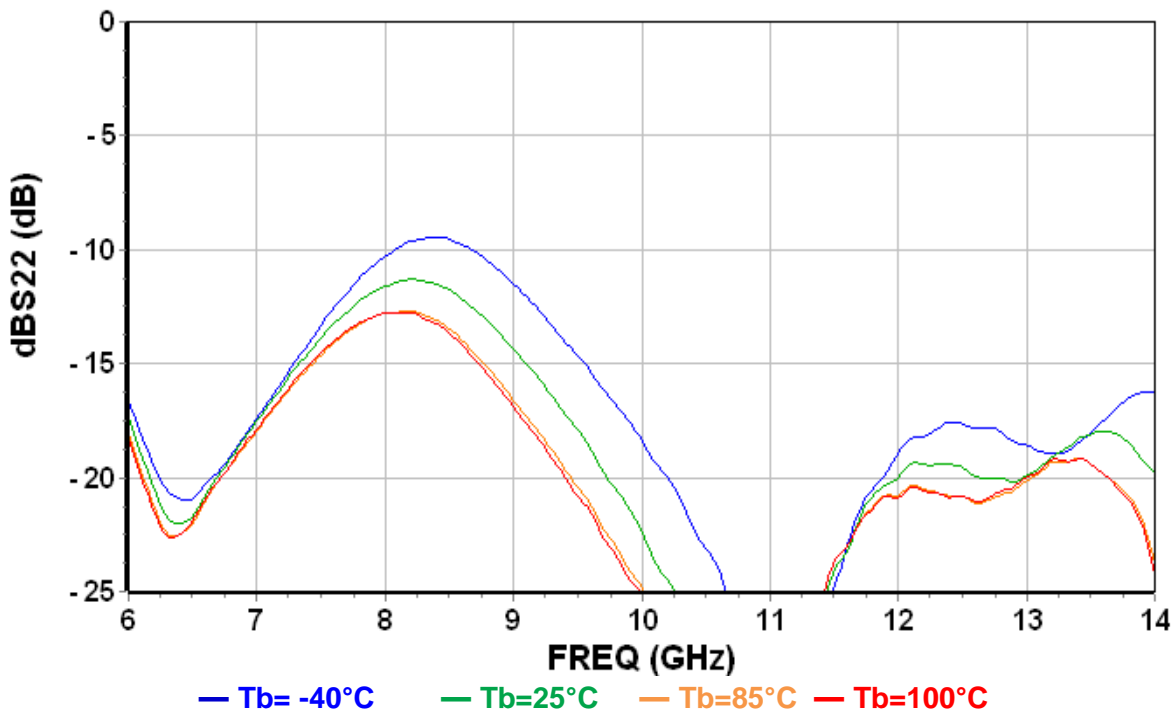
Typical Test Fixture Measurements: Small Signal Performances

Pulsed measurements (25 μ s / 10% Duty Cycle): $T_b = -40^\circ\text{C}/+25^\circ\text{C}/+85^\circ\text{C}/100^\circ\text{C}$,
 $V_d = 20\text{V}$, $I_{dq} = 320\text{mA}$ (kept constant versus temperature)

Input Return Loss versus Frequency

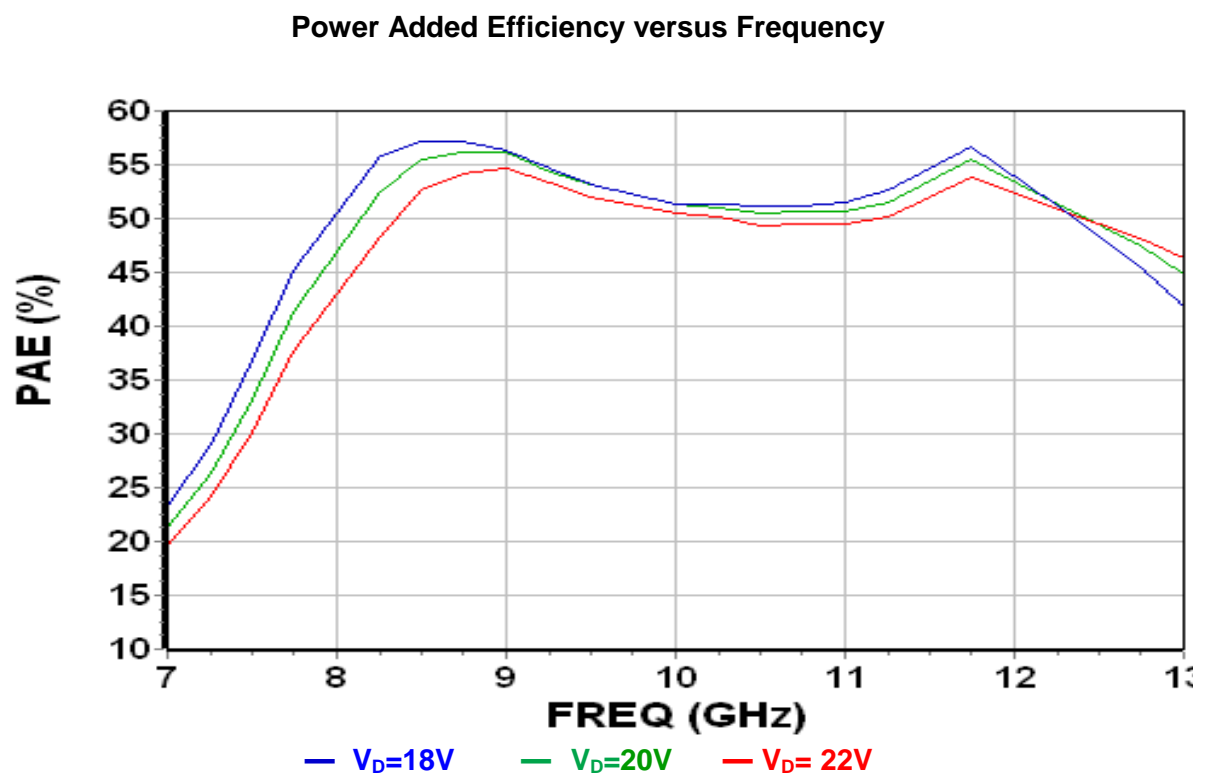
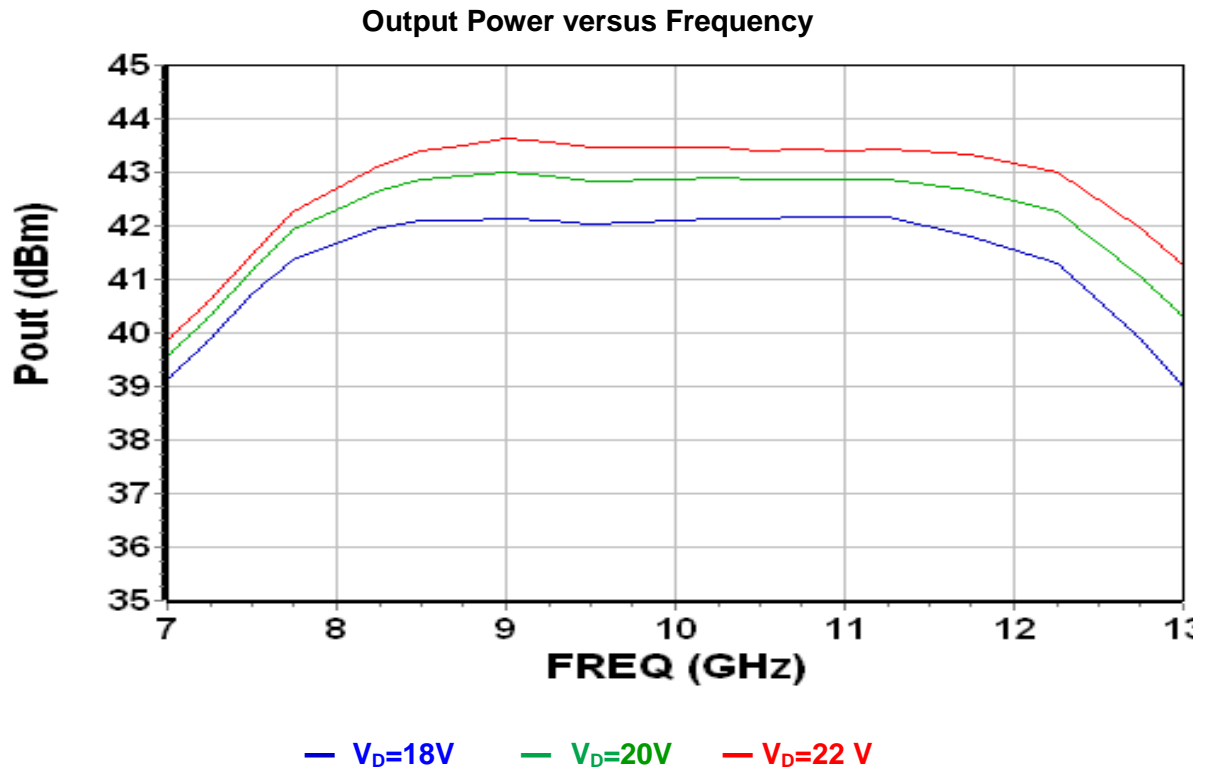


Output Return Loss versus Frequency



Typical Test Fixture Measurements: Non-linear performances

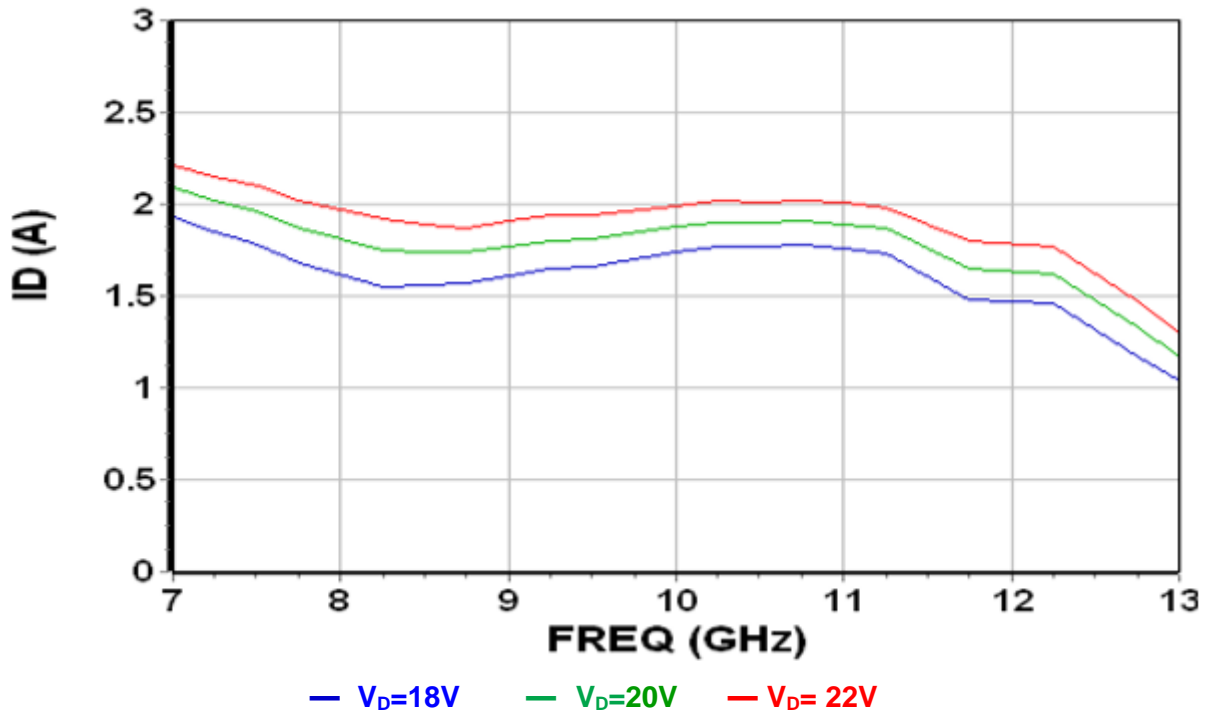
Pulsed measurements at saturation (25µs / 10% Duty Cycle):
 Tb=+25°C, Pin = 23dBm, Idq =320mA



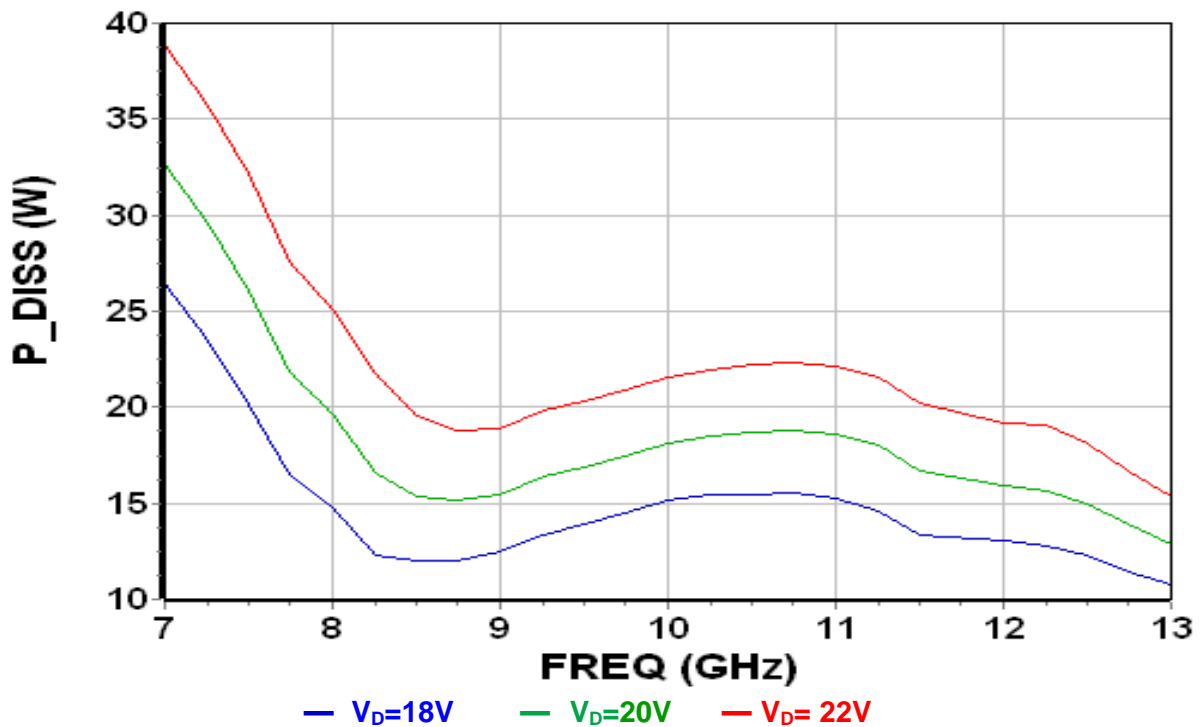
Typical Test Fixture Measurements: Non-linear performances

Pulsed measurements at saturation
 (25 μ s / 10% Duty Cycle): $T_b=+25^\circ\text{C}$, $I_{dq}= +320\text{mA}$

Drain Current versus Frequency



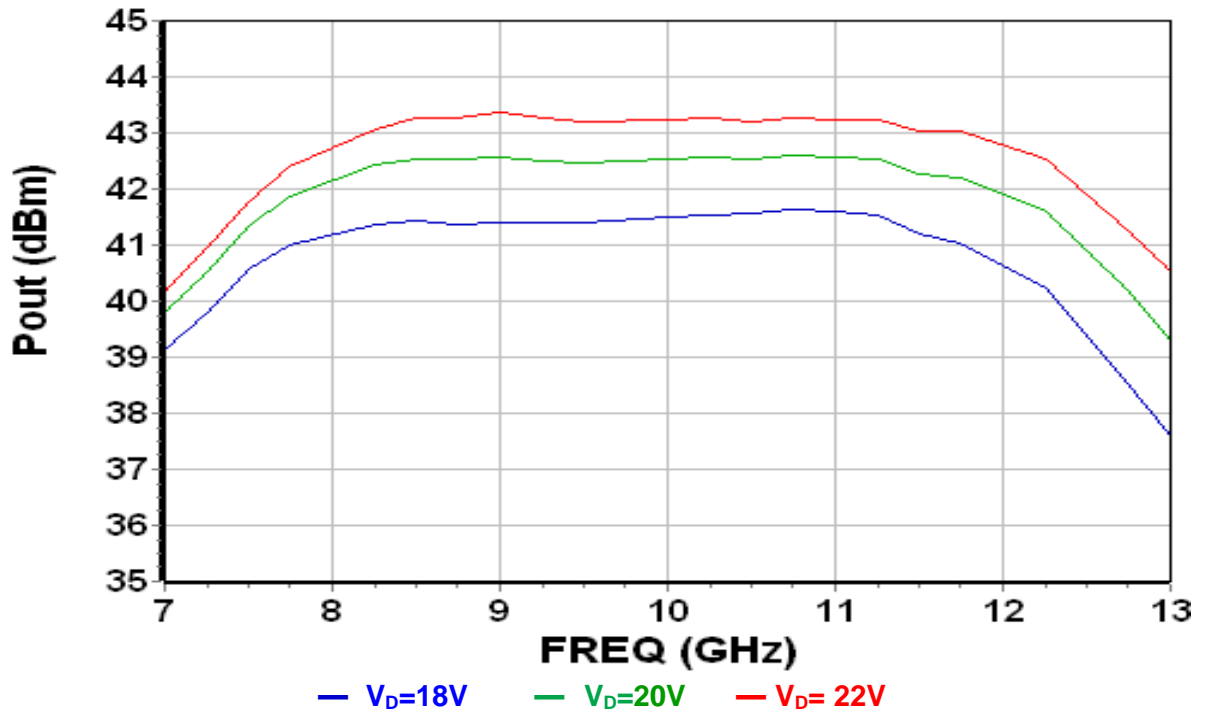
Dissipated Power versus Frequency



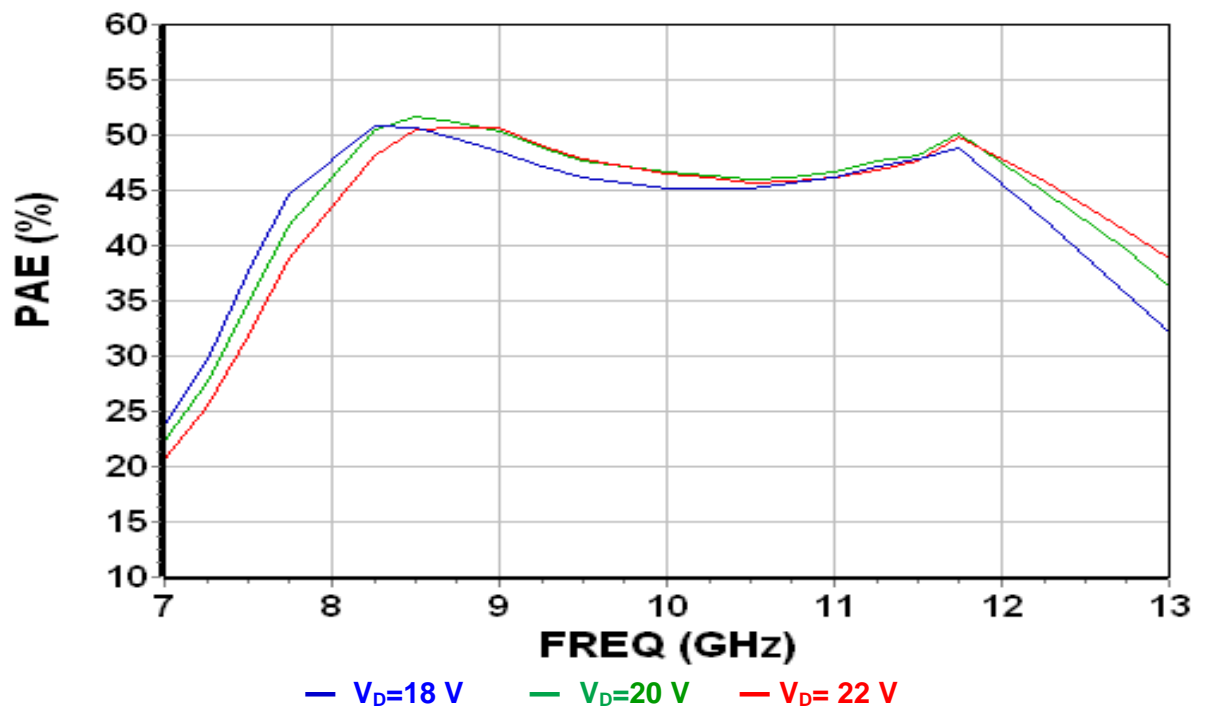
Typical Test Fixture Measurements: Non-linear performances

Pulsed measurements at saturation (25 μ s / 10% Duty Cycle):
 Tb=+85°C, Vd = +20V, Idq = 320 mA

Output Power versus Frequency

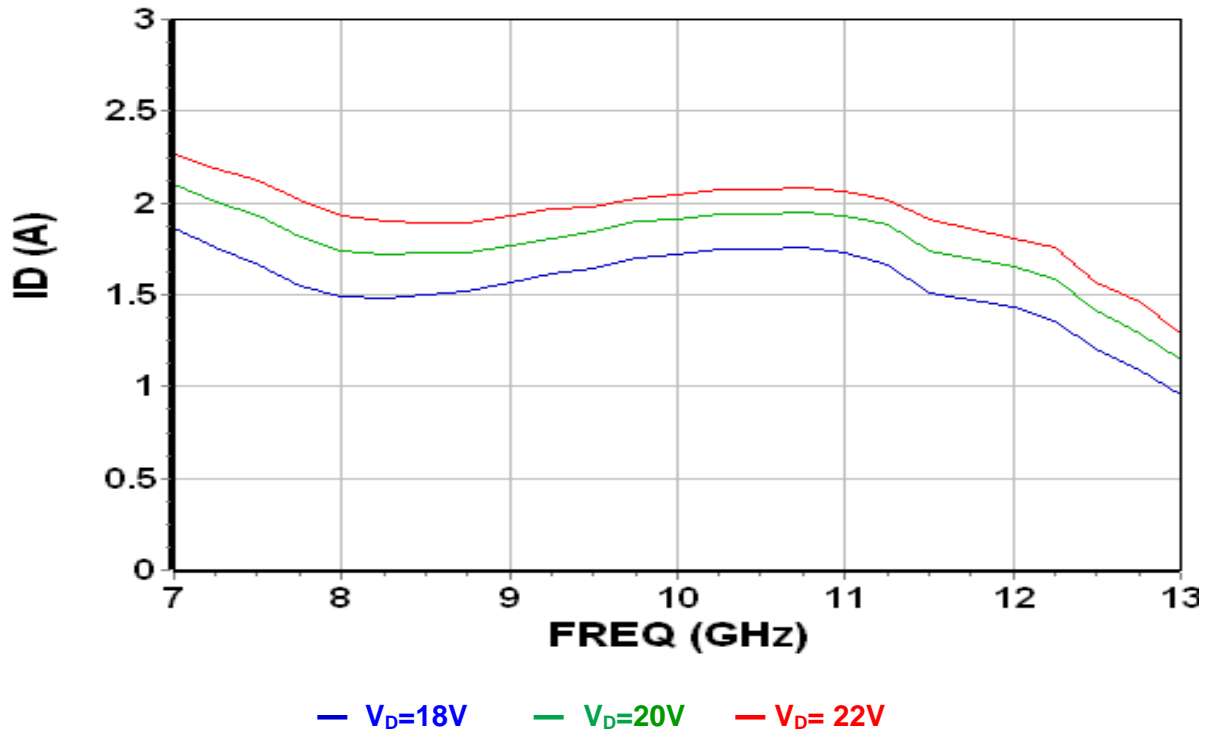


Power Added Efficiency versus Frequency

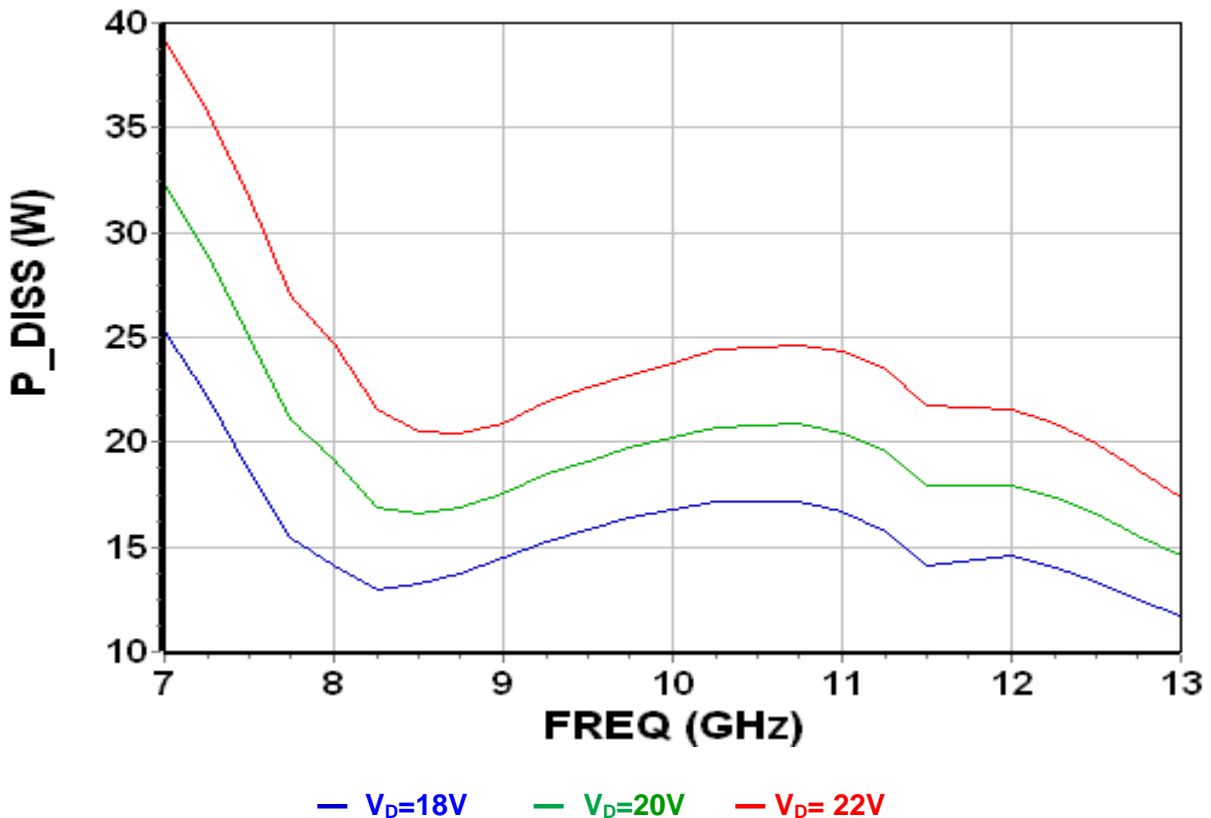


Typical Test Fixture Measurements: Non-linear performances

Drain Current versus Frequency



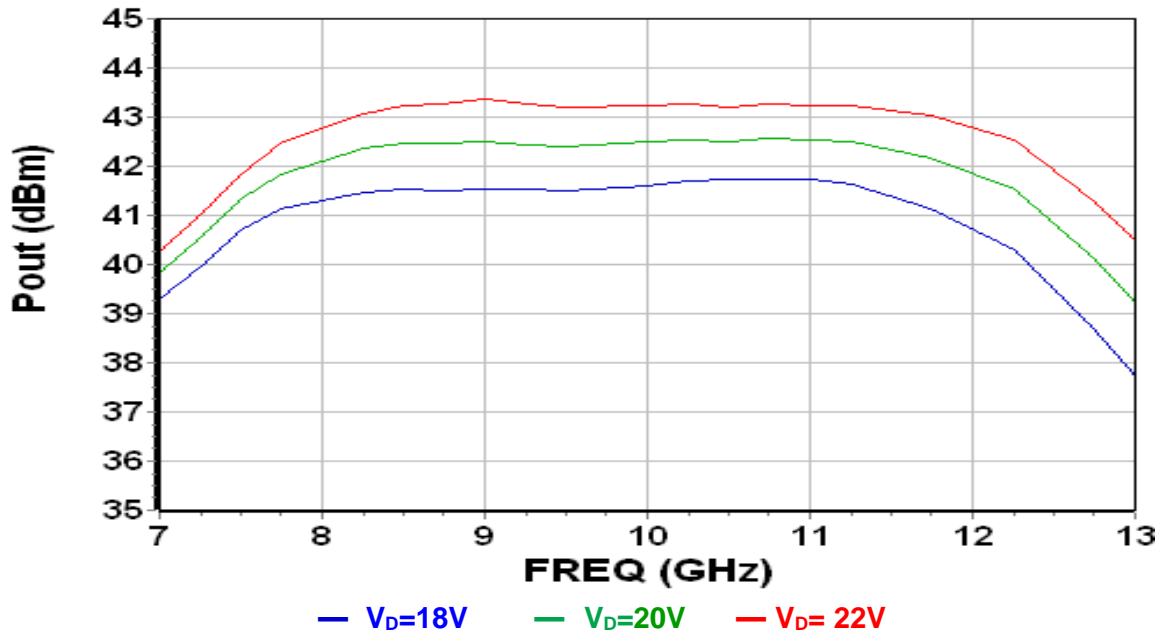
Dissipated Power versus Frequency



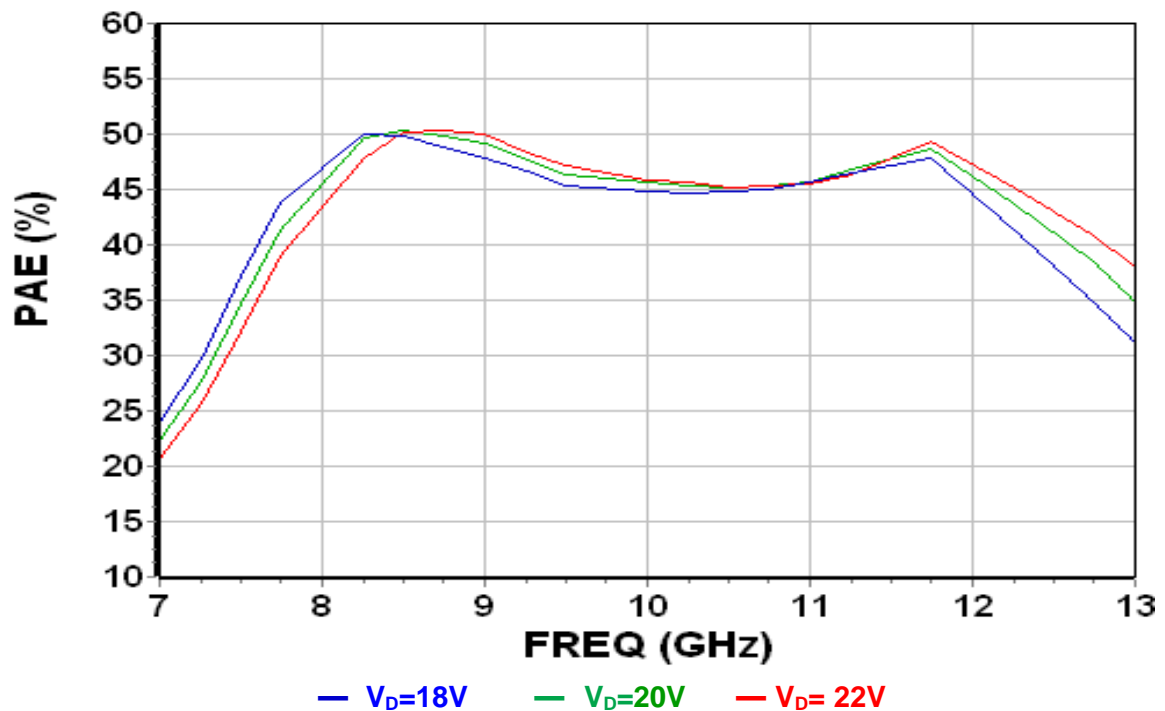
Typical Test Fixture Measurements: Non-linear performances

Pulsed measurements at saturation (25µs / 10% Duty Cycle):
 Tb=+ 100°C, Vd = +20V, Idq = 320mA

Output Power versus Frequency

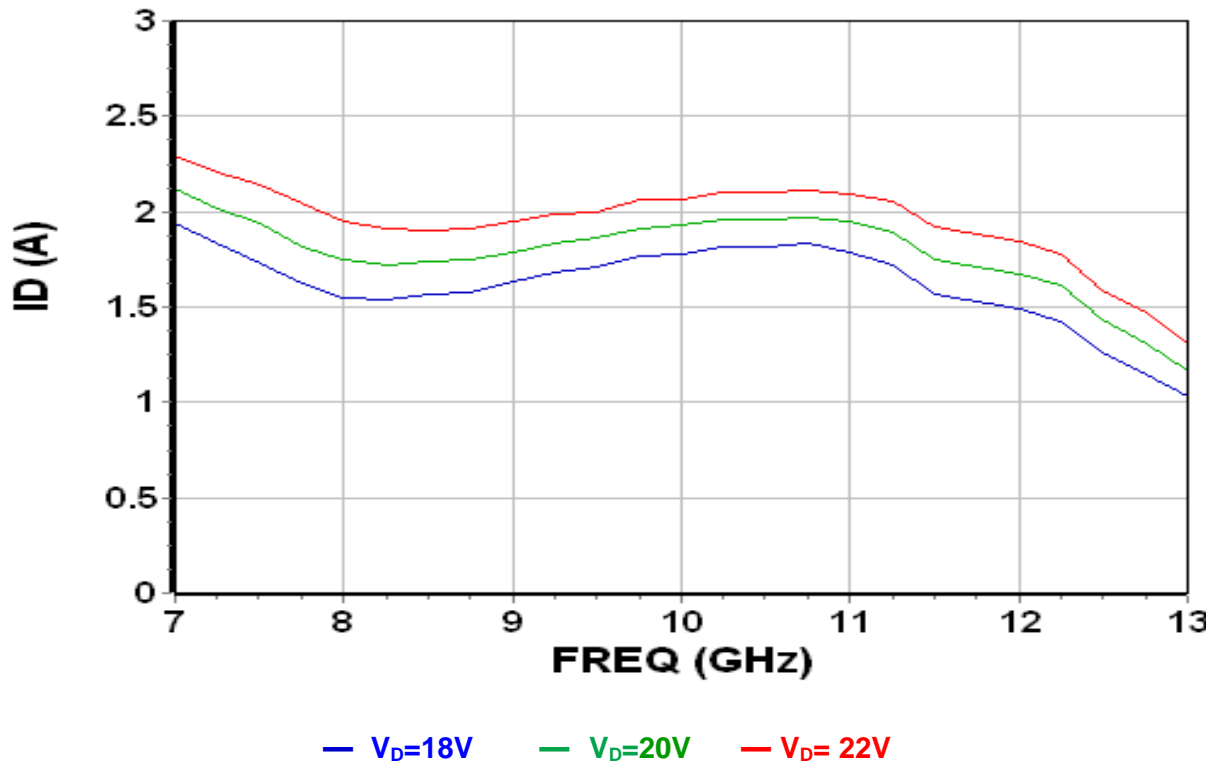


Power Added Efficiency versus Frequency

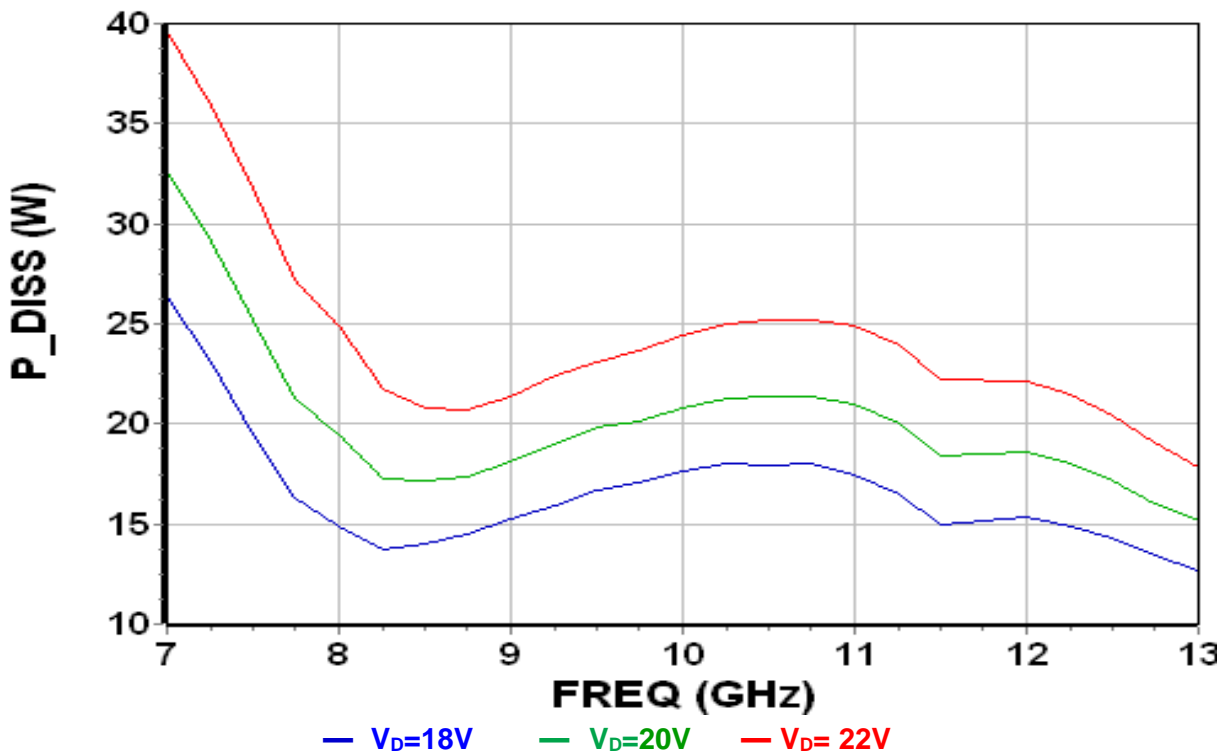


Typical Test Fixture Measurements: Non-linear performances

Drain Current versus Frequency



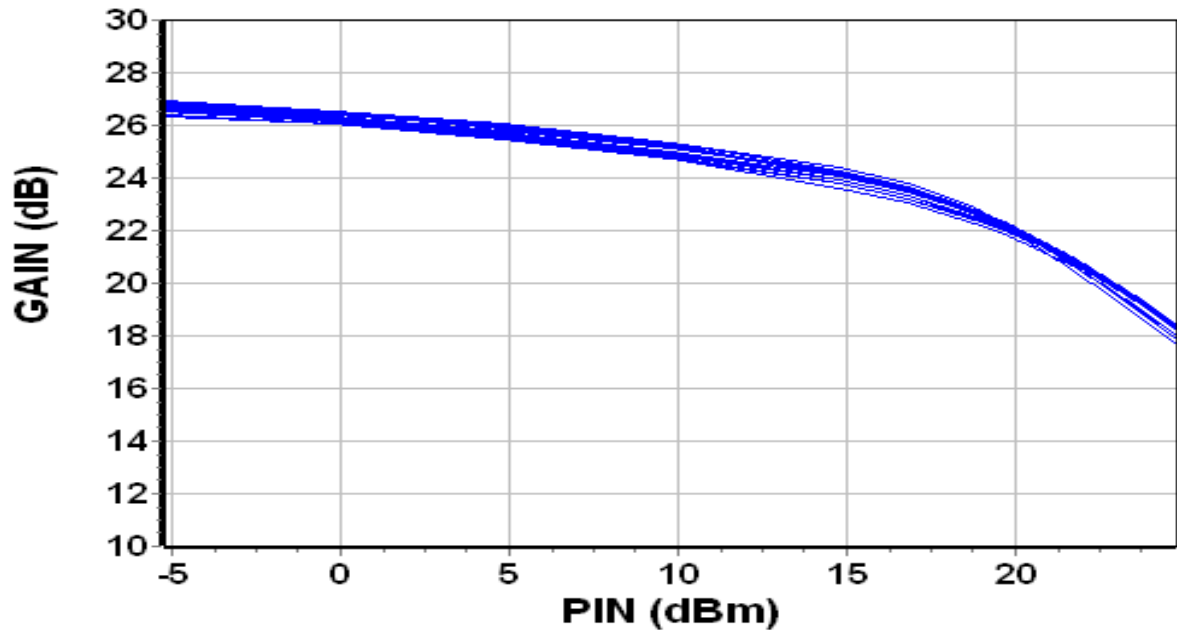
Dissipated Power versus Frequency



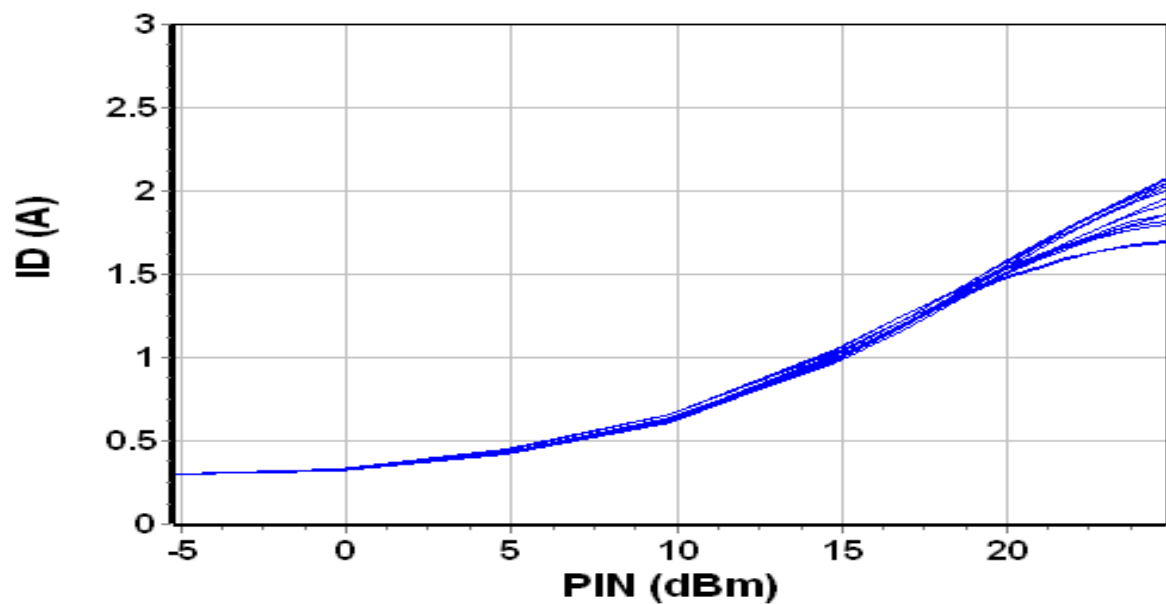
Typical Test Fixture Measurements: Non-linear Performances

Pulsed measurements (25µs / 10% Duty Cycle):
 Tb.= 25°C, Vd =+20V, Iqd =320 mA, Pin range : -5 to 25dBm
 Frequency range: 8-12 GHz step 0.25GHz

Gain versus Input Power



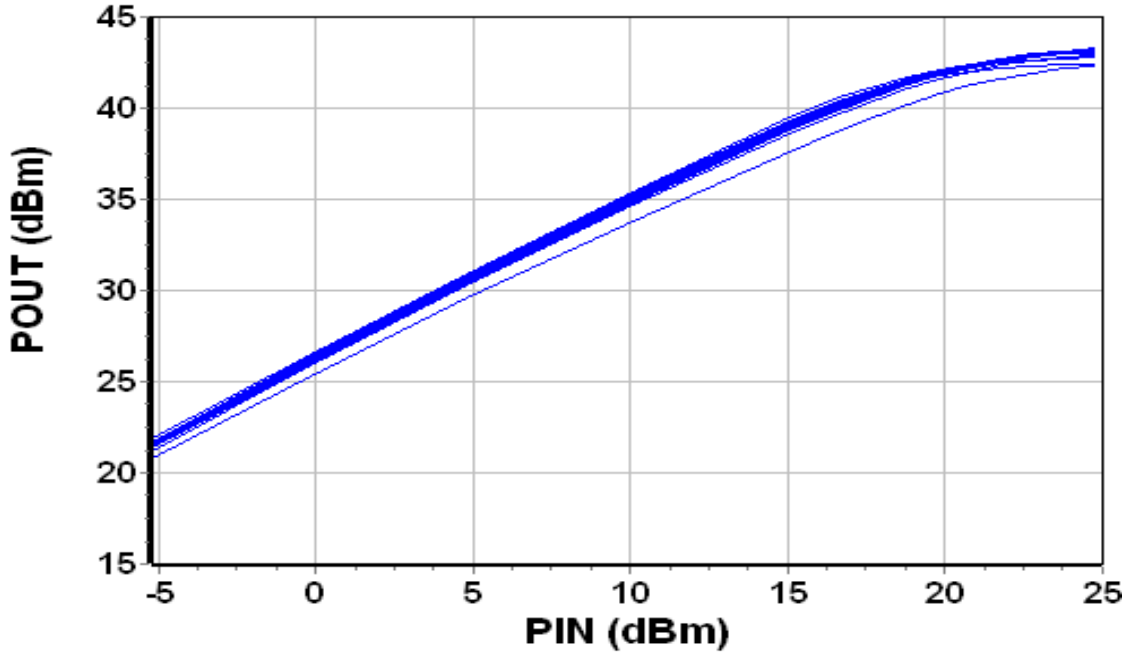
Id versus Input Power



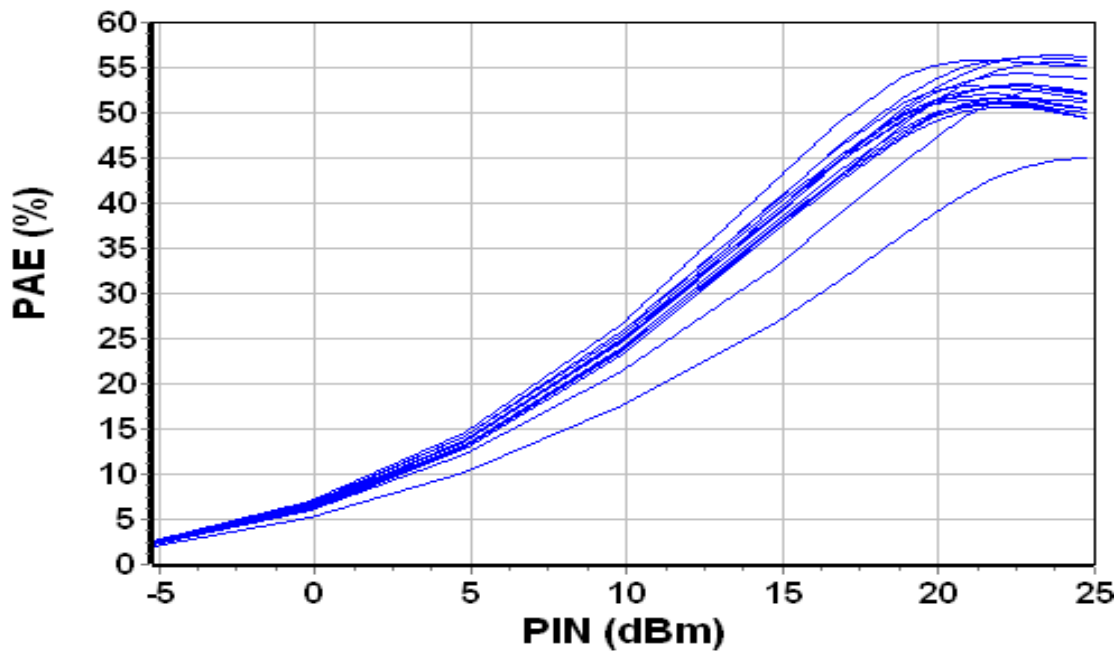
Typical Test Fixture Measurements: Non-linear Performances

Pulsed measurements (25 μ s / 10% Duty Cycle):
Tb.= 25°C, Vd = +20V, Iqd =320mA, Pin range : -5 to 25dBm
Frequency range: 8-12GHz step 0.25GHz

Pout versus Input Power



PAE versus Input Power

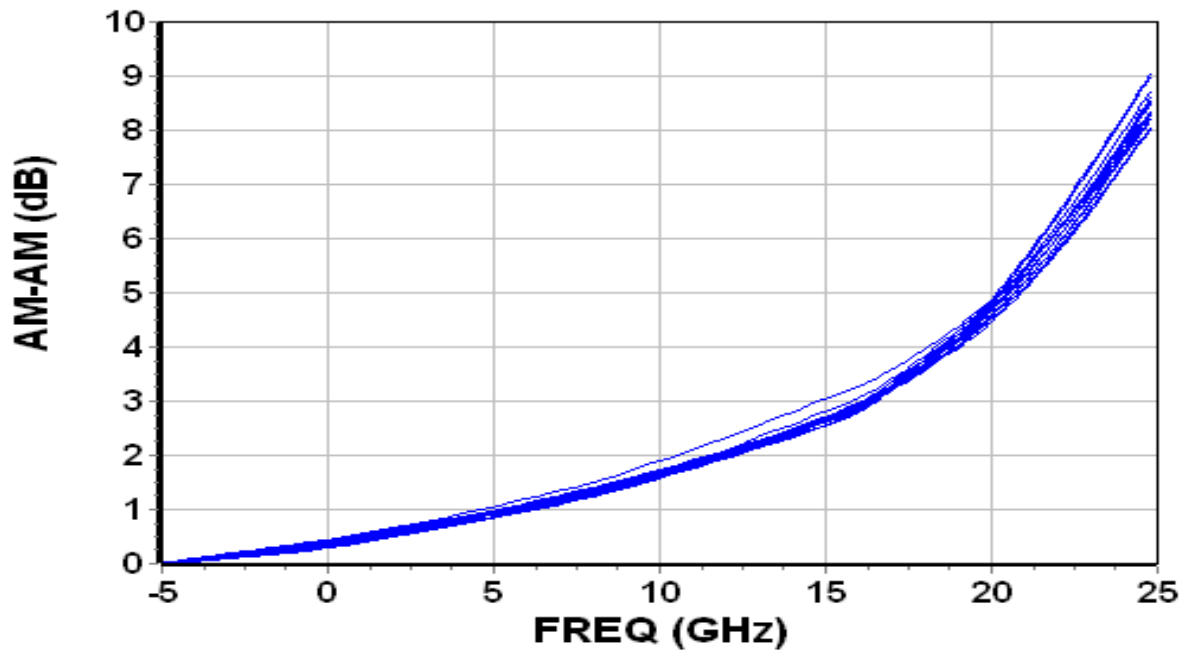
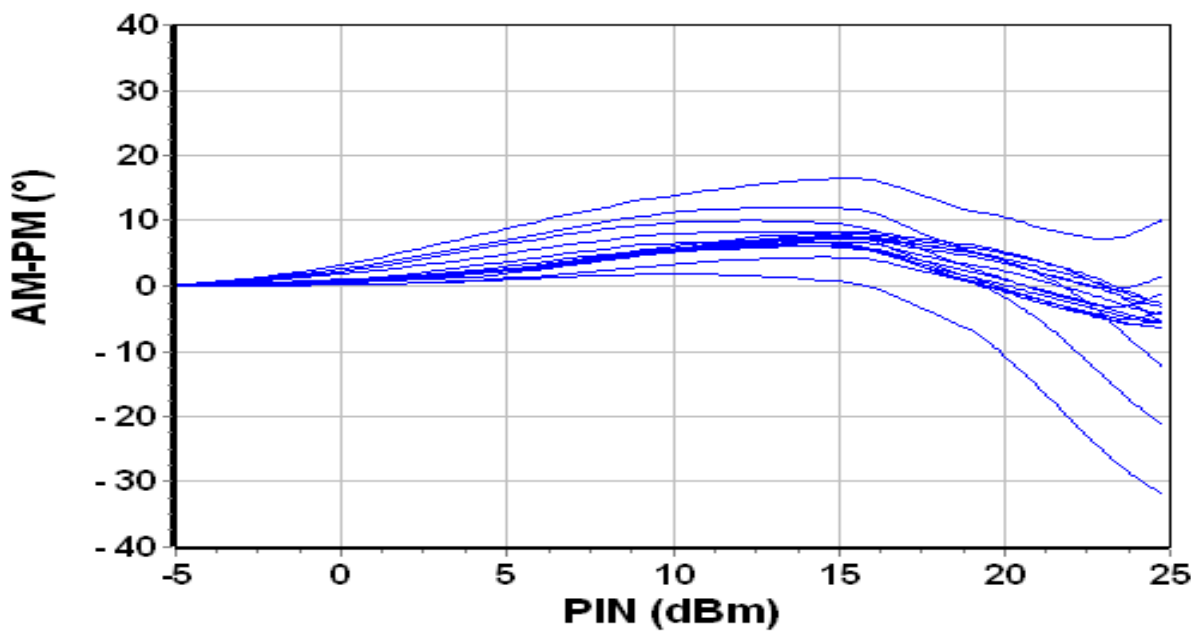


Typical Test Fixture Measurements: Non-linear Performances

Pulsed measurements (25 μ s / 10% Duty Cycle):

Tb.= 25°C, Vd = +20V, Iqd =320mA, Pin range : -5 to 25dBm

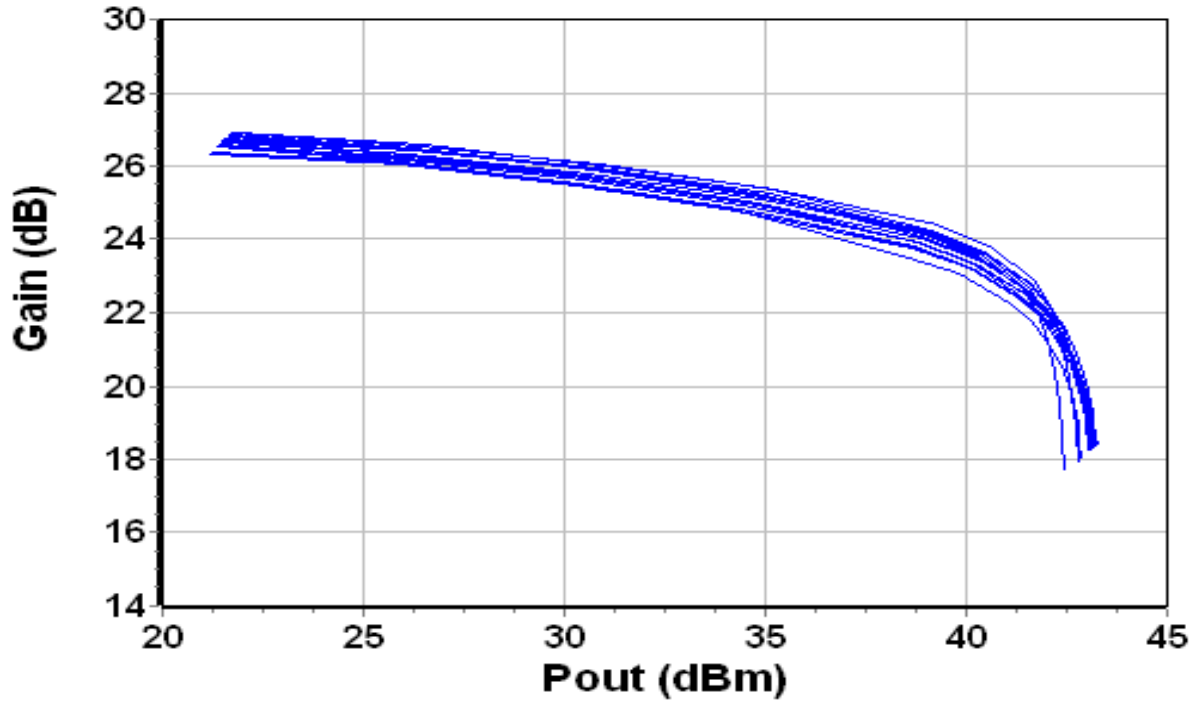
Frequency range: 8-12GHz step 0.25 GHz

AM-AM versus Input Power**AM-PM versus Input Power**

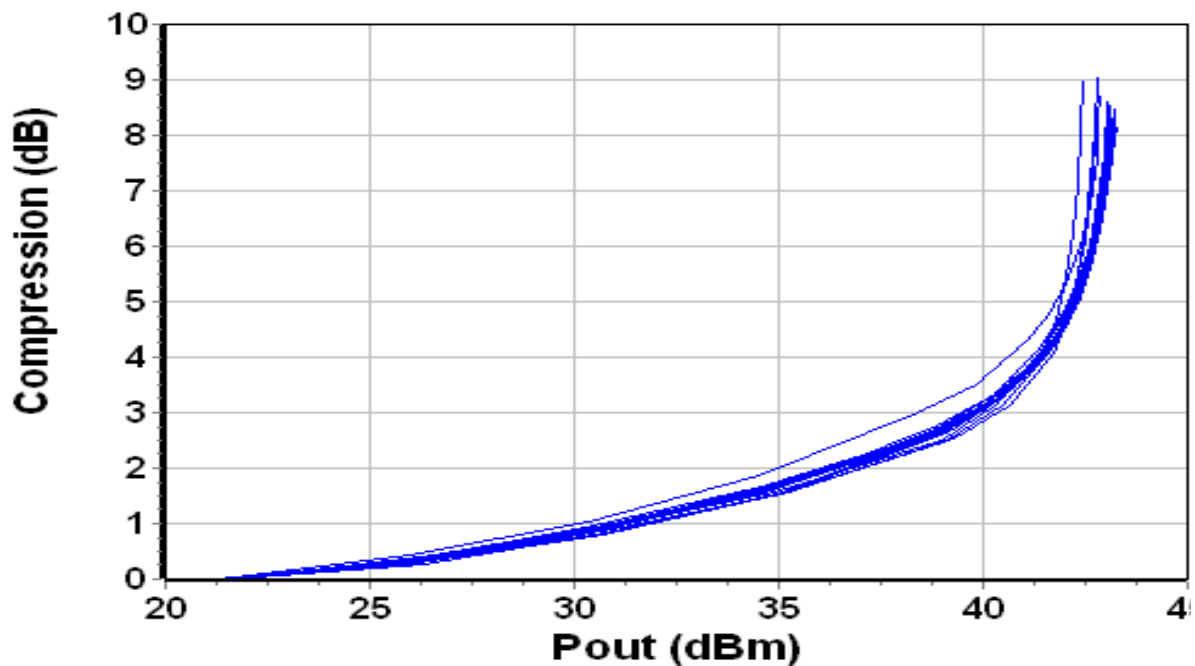
Typical Test Fixture Measurements: Non-linear Performances

Pulsed measurements (25 μ s / 10% Duty Cycle):
Tb.= 25°C, Vd = +20V, Iqd =320 mA, Pin range : -5 to 25dBm
Frequency range: 8-12GHz step 0.25GHz

Gain versus Output Power



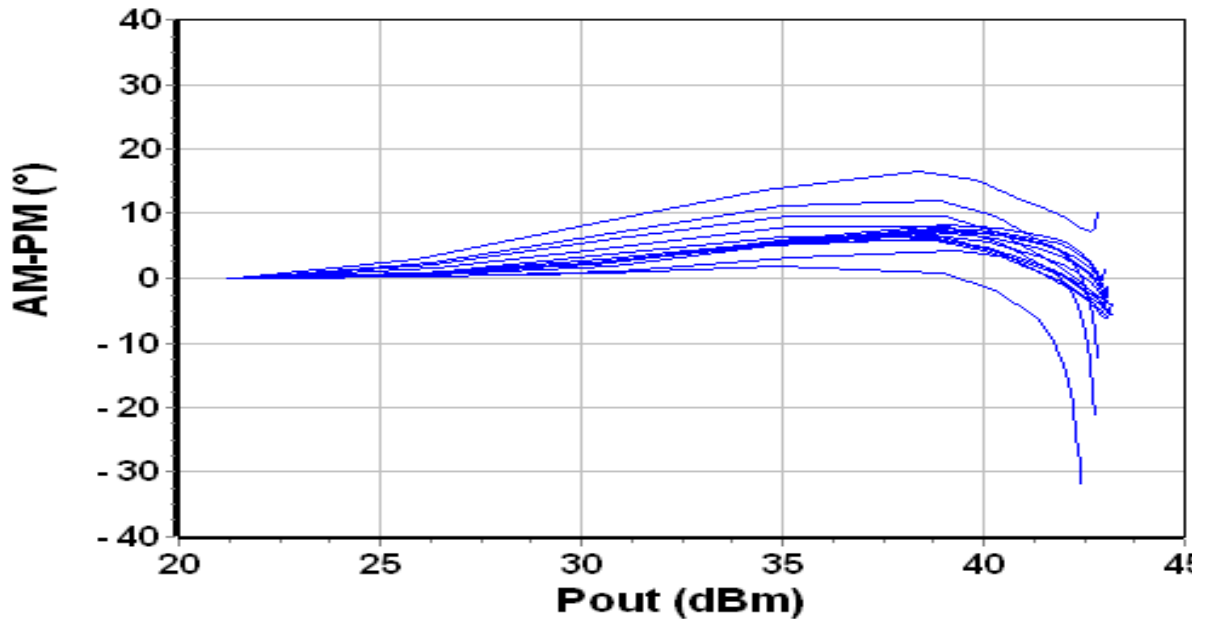
Compression versus Output Power



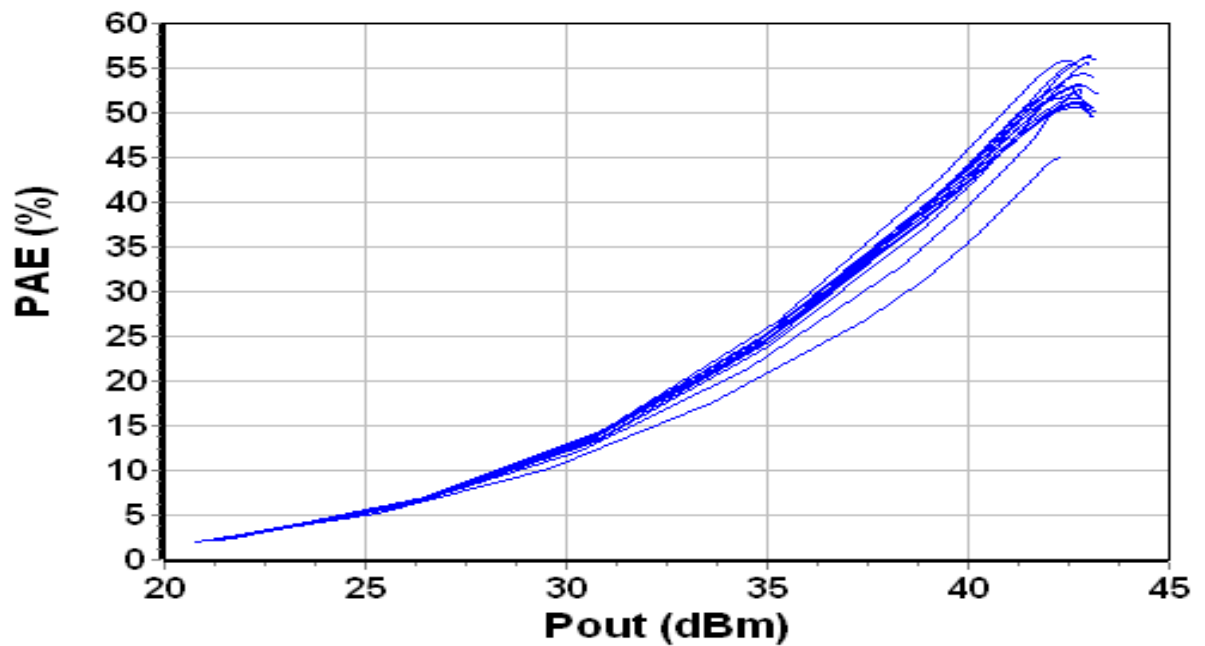
Typical Test Fixture Measurements: Non-linear Performances

Pulsed measurements (25µs / 10% Duty Cycle):
 Tb.= 25°C, Vd = +20V, Iqd =320mA, Pin range : -5 to 25dBm
 Frequency range: 8-12GHz step 0.25GHz

AM-PM conversion versus Output Power



Power Added Efficiency versus Output Power



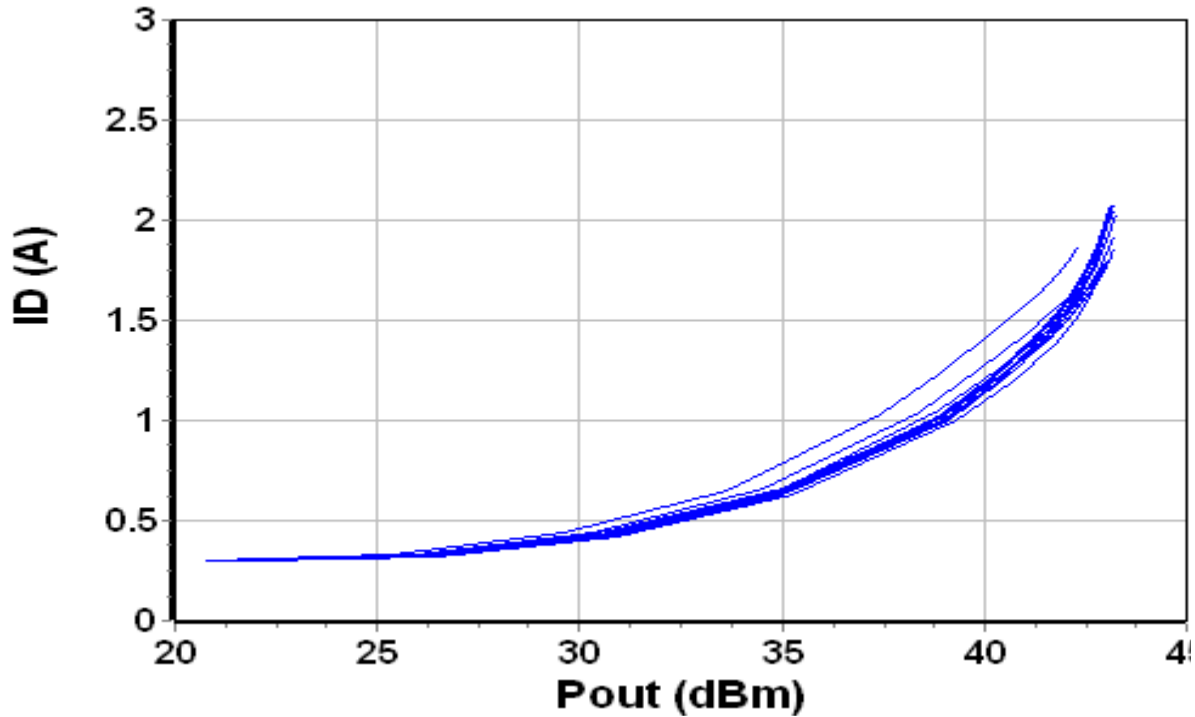
Typical Test Fixture Measurements: Non-linear Performances

Pulsed measurements (25 μ s / 10% Duty Cycle):

Tb.= 25°C, Vd = +20V, Iqd =320mA, Pin range : -5 to 25dBm

Frequency range: 8-12GHz step 0.25GHz

Drain current versus Output Power

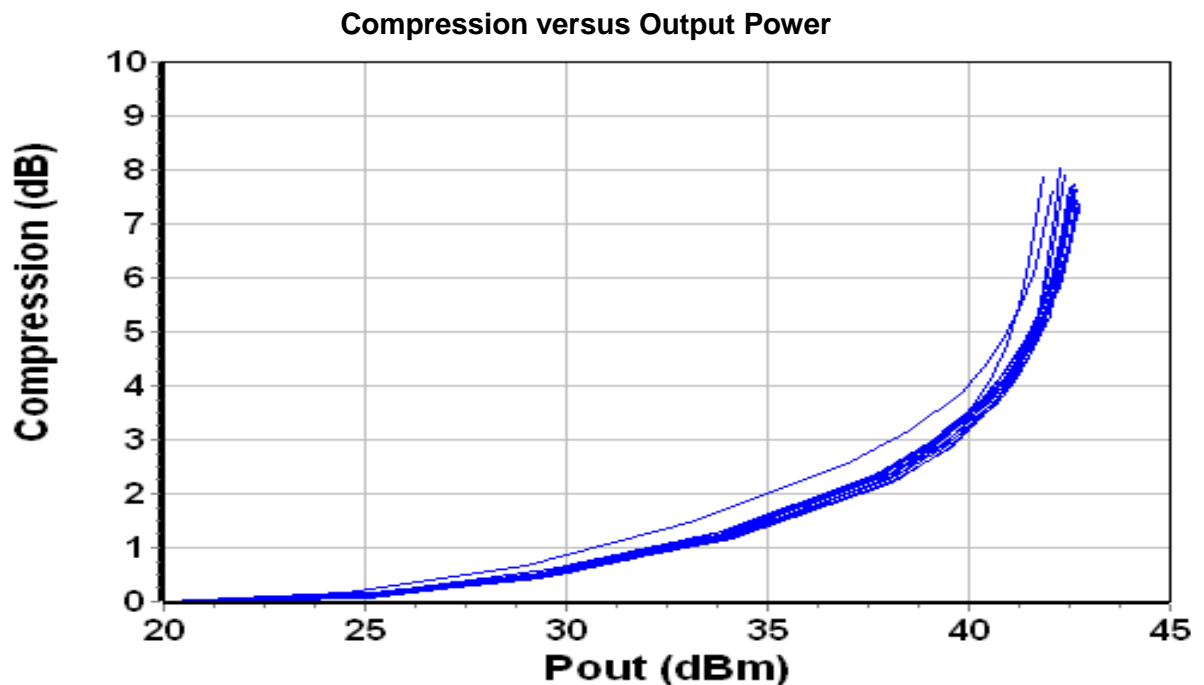
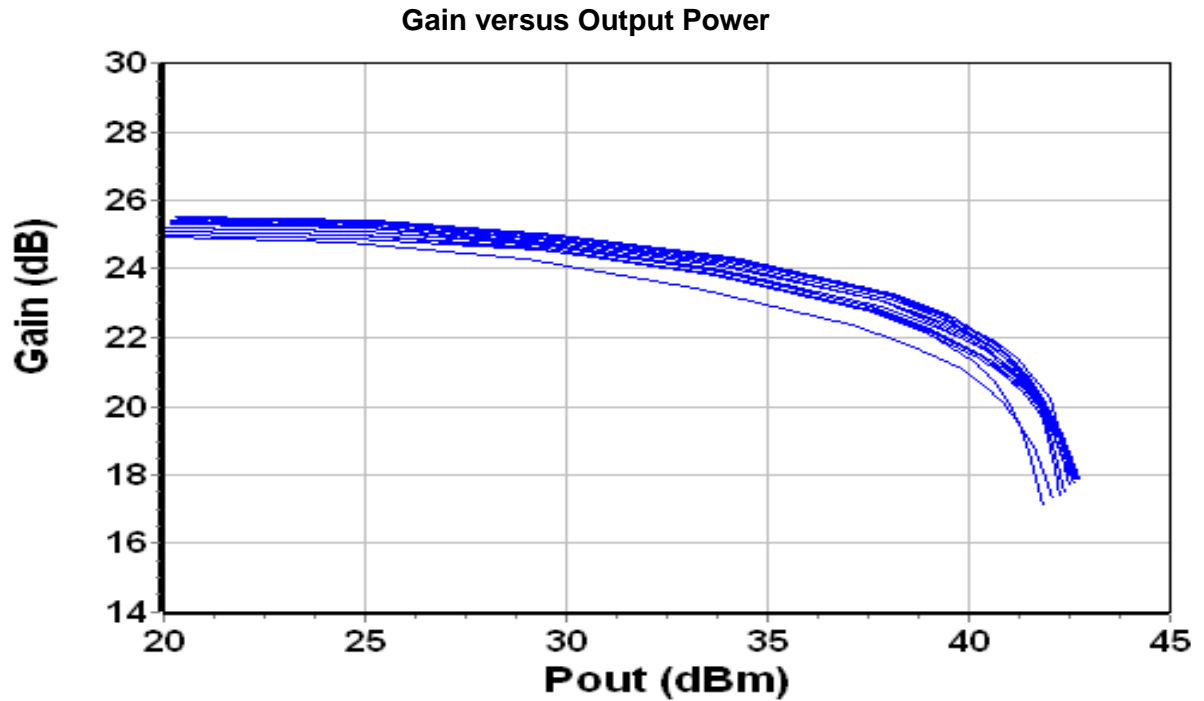


Typical Test Fixture Measurements: Non-linear Performances

Pulsed measurements (25µs / 10% Duty Cycle):

Tb.= 100 °C, Vd = +20V, Iqd =320mA, Pin range : -5 to 25dBm

Frequency range: 8-12GHz step 0.25GHz



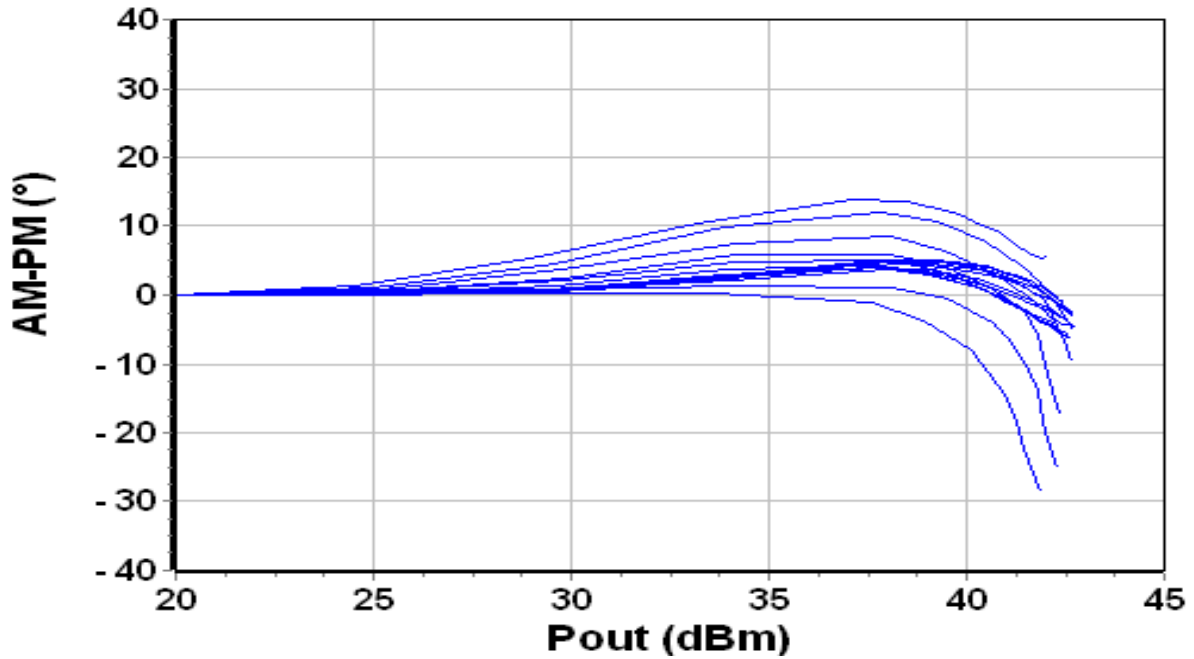
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Pulsed measurements (25 μ s / 10% Duty Cycle):

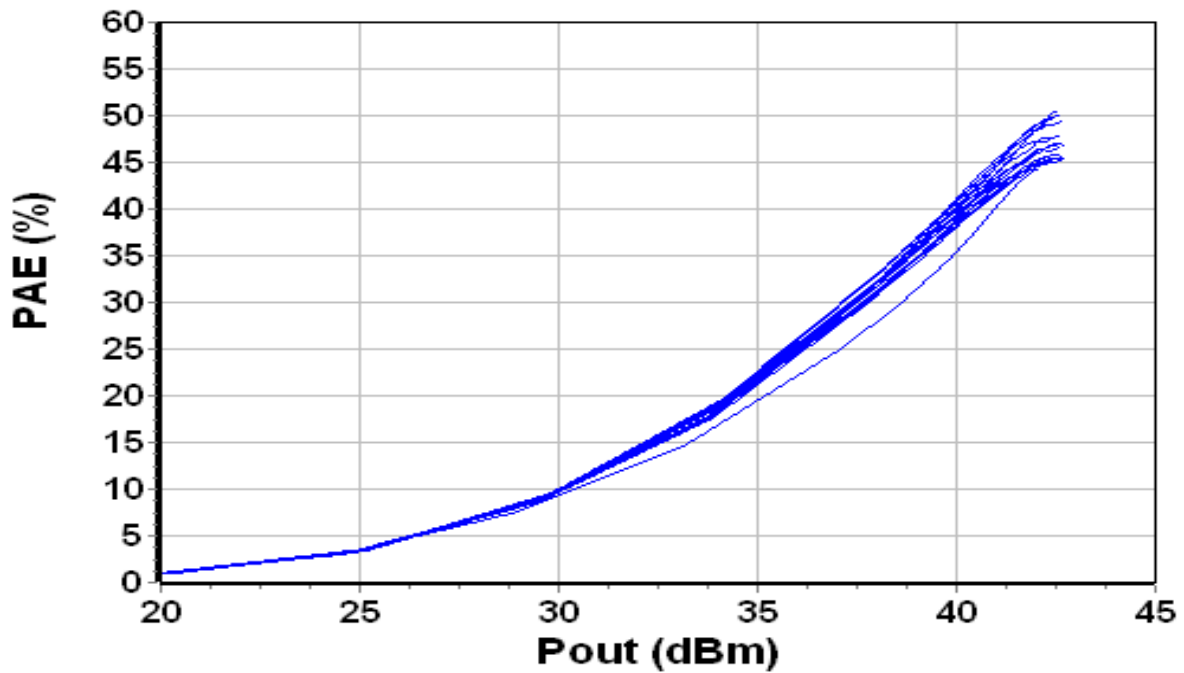
Tb.= 100 °C, Vd = +20V, Iqd =320mA, Pin range : -5 to 25dBm

Frequency range: 8-12GHz step 0.25GHz

AM-PM conversion versus Output Power

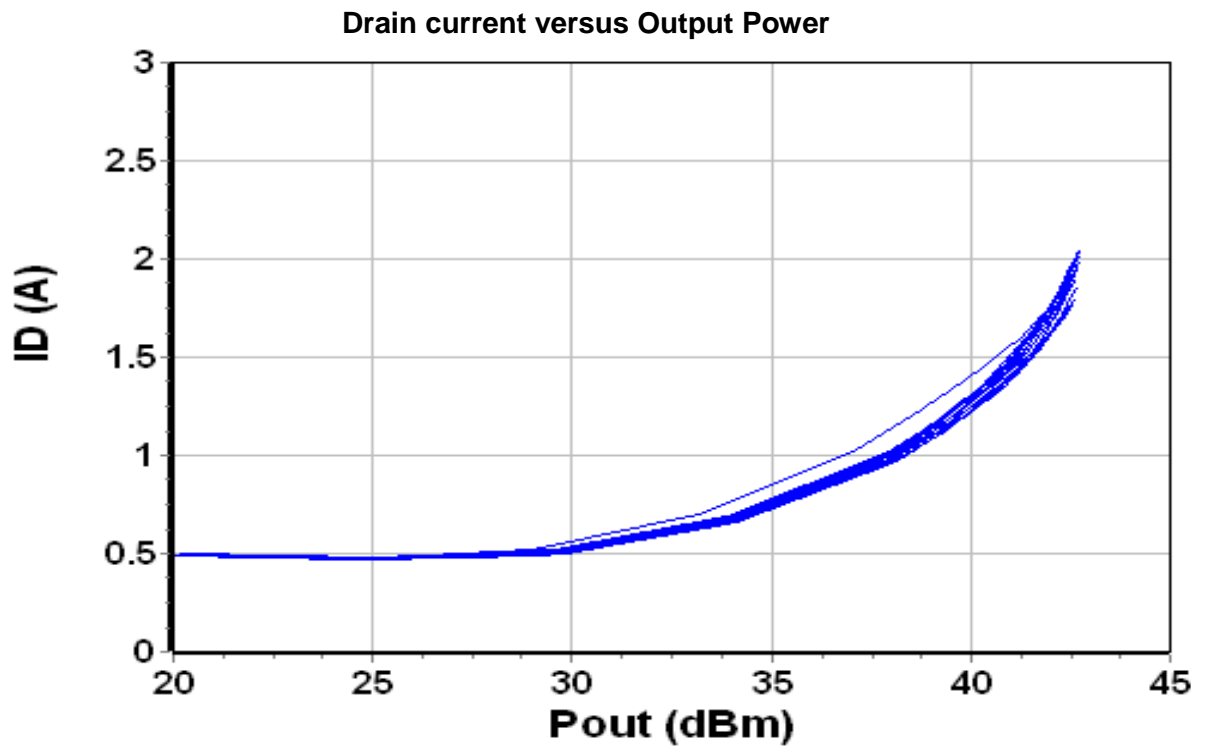


Power Added Efficiency versus Output Power

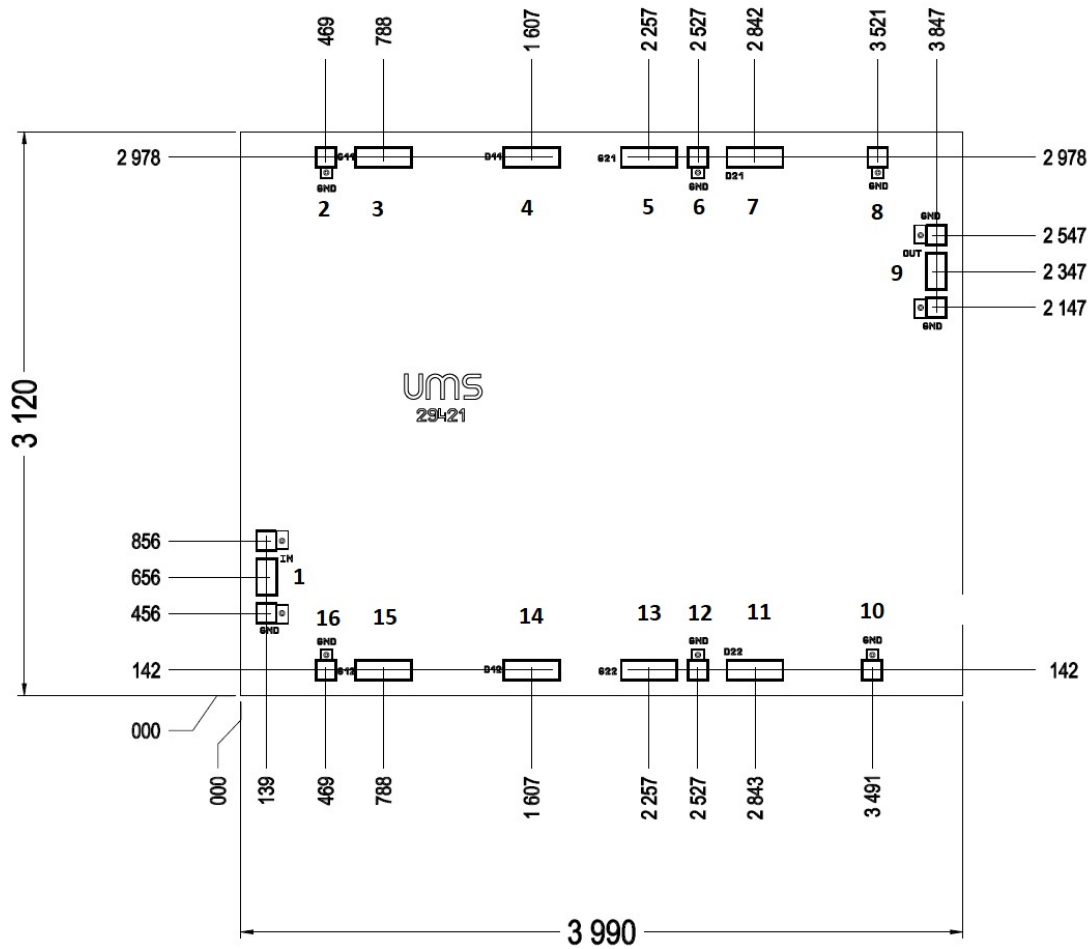


Typical Test Fixture Measurements: Non-linear PerformancesPulsed measurements (25 μ s / 10% Duty Cycle):**T_b** = 100 °C, V_d = +20V, I_{qd} = 320mA, Pin range : -5 to 25dBm

Frequency range: 8-12 GHz step 0.25 GHz



Chip Mechanical data



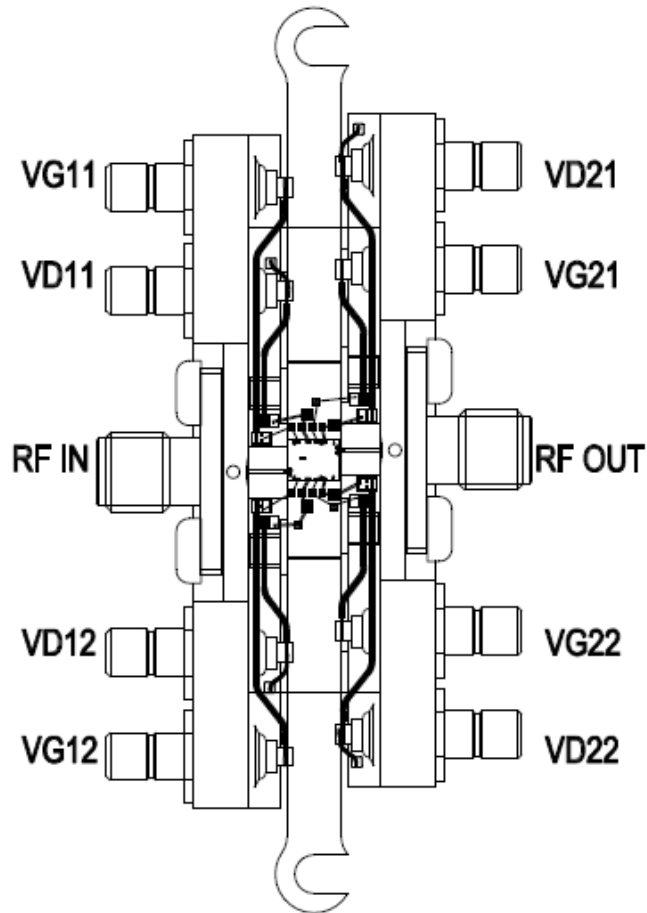
Chip size = 3990x3120 ±50μm
 Chip thickness = 70 μm ±10μm

Chip width and length are given with a tolerance of ±50μm
 RF pads (1, 9) = 206 x 116μm²

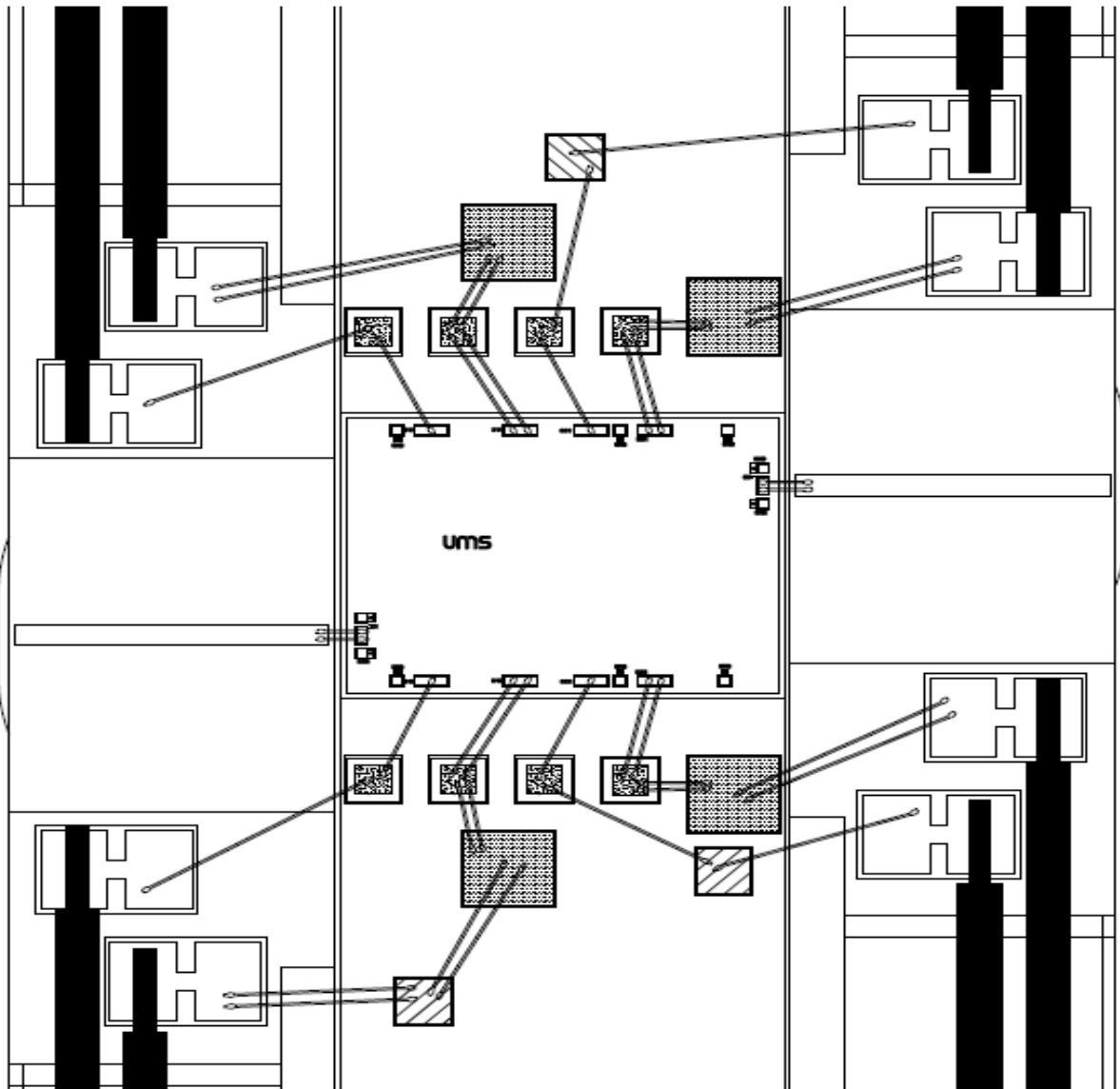
DC pads (2, 6, 8, 10, 12, 16) = 118 x 118μm²
 DC pads (3, 4, 5, 7, 11, 13, 14, 15) = 318 x 118μm²

PAD Number	Name	Description
1	IN	RF input
2, 6, 8, 10, 12, 16	GND	Ground (Not connected)
3, 15	VG1	Gate voltage of 1 st stage
5, 13	VG2	Gate voltage of 2 nd stage
4, 14	VD1	Drain voltage of 1 st stage
7, 11	VD2	Drain voltage of 2 nd stage
9	OUT	RF output

Recommended Test Jig



Recommended assembly plan



3 levels of decoupling capacitor have been used on drain accesses:
First level of capacitor is 120pF, second level is 10nF and third level is 100nF. Only 120pF and 10nF capacitors can be seen on the previous assembly drawing (close to the chip).

2 levels of decoupling capacitor have been used on gate accesses:
First level of capacitor is 120pF, second level is 10nF and third level is 100nF.

Note: Supply feed should be bypassed. 25 μ m diameter gold wire is to be preferred.

Notes:



Recommended ESD management

Refer to the application note AN0020 available at <https://www.ums-rf.com> for ESD sensitivity and handling recommendations for the UMS products.

Recommended environmental management

UMS products are compliant with the regulation in particular with the directives RoHS N°2011/65 and REACH N°1907/2006. More environmental data are available in the application note AN0019 also available at <https://www.ums-rf.com>.

Recommended reflow process assembly

Refer to the application note AN001 available at <https://www.ums-rf.com> for die attach.

Ordering Information

Chip form:

CHA8312-99F/00

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